# 新世代均勻性改善及鍍薄銅填孔電鍍銅技術

## New Generation Via Filling Acid Copper Plating Technics for Improving Distribution Uniformity and Thinner Copper

### MICROFILL™ SFP Acid Copper

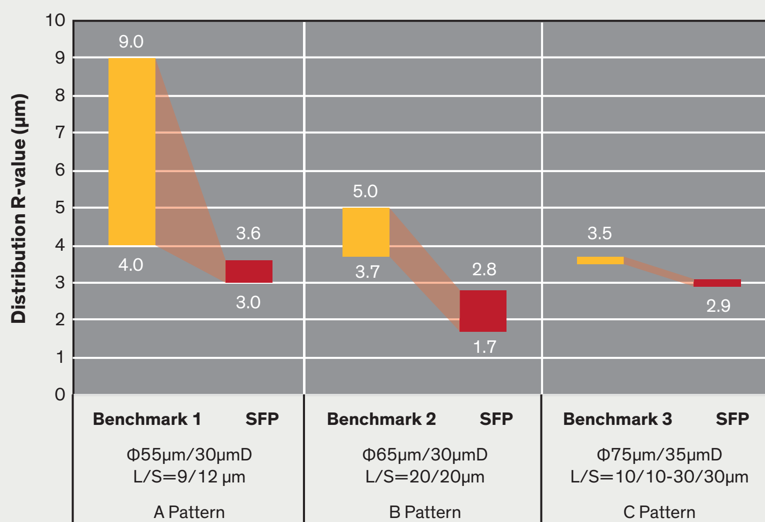
MICROFILL™ SFP Acid Copper is a new generation via-filling acid copper which applies for IC Substrate, and to optimize mSAP yield rate, and enable advanced RDL technics. The outstanding distribution uniformity performance in pattern PCBs enables the industry to achieve higher yield rate, and the thinner platting thickness enhance the technics for advanced fine pitch requirements.

MICROFILL™ SFP Acid Copper為新世代應用於IC Substrate 與優化mSAP良率並實現先進RDL技術之填孔鍍銅添加劑。其在圖型電鍍上優越的均鍍能力使得產業能達成更高的產品良率，且其鍍薄銅的能力實現了先進細線路的需求。

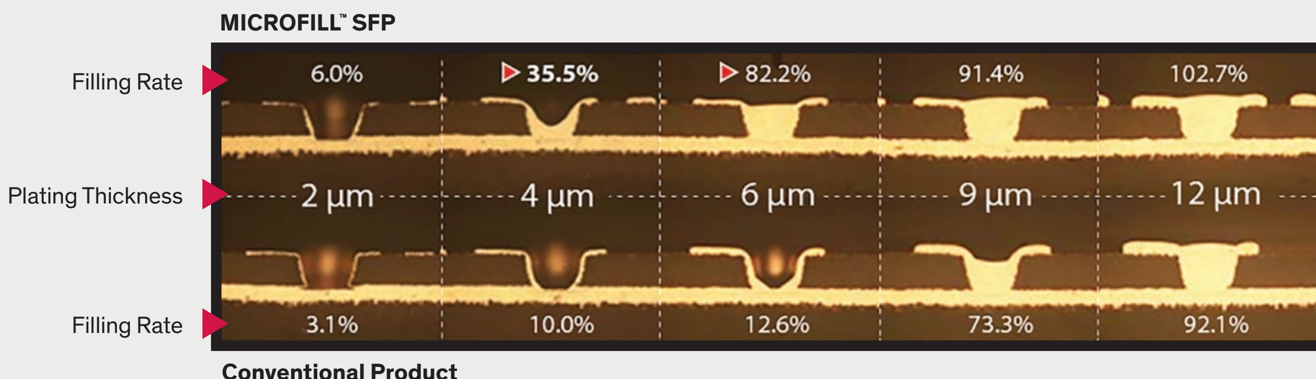
### Advantages 優點

- Filling up blind vias in lower plating thickness
  在更低的鍍厚下填滿盲孔
- Outstanding distribution uniformity
  優越的均鍍力
- In higher sulfuric acid (VMS) still works well of blind vias filling
  在高酸(VMS)環境下仍能填滿盲孔

- MICROFILL™ SFP provides better pattern plating distribution
  MICROFILL™ SFP 提供更好的圖型電鍍均勻性




- MICROFILL™ SFP has faster via-filling mechanism (Spec: 60 μmØ / 40 μmd)
  MICROFILL™ SFP能更快達成填孔機制

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